

# **Inductors**

RF chokes, BC+ series

Series/Type:

Date:

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### **Inductors**

### RF chokes, BC+ series

B78108E, B78148E

#### **BC** chokes

Rated inductance 0.1 µH ... 100 µH Rated current 640 mA .. 7300 mA

#### Construction

- Ferrite drum core
- Winding: enamel copper wire
- Flame-retardant lacquer coating

#### **Features**

- Very high rated current
- High saturation behaviour
- High self-resonance frequency
- Suitable for wave soldering
- RoHS-compatible

## **Applications**

- DC-DC converter
- Filtering of supply voltage & battery charger (EMI)
- RF blocking and filtering
- Decoupling and interference suppression
- For telecommunications, LED and energy-saving lamps, solar LED lamps, entertainment electronics

#### **Terminals**

- Radially bent to 5mm lead spacing (B78148E)
- Central axial leads (B78108E)
- Base material Cu
- Electroplated with nickel and pure tin

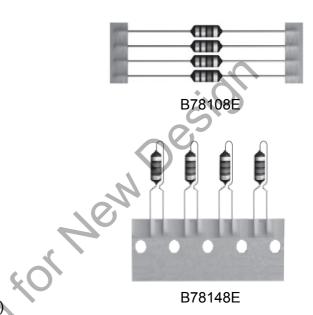
## Marking

Inductance indicated by color bands in accordance with IEC 60062

### Delivery mode and packing units

- Taped, Ammo and reel packing
- Packing units:

	Ammo	Reel
	(pcs./pack.)	(pcs./reel)
Axial	2500	5000
Radial	2500	2000



B78148E

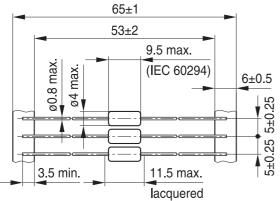


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## **Dimensional drawings**

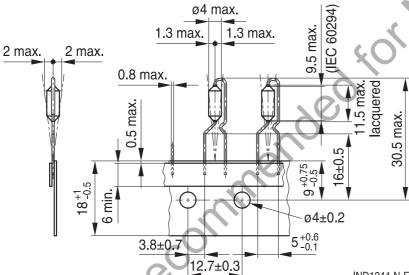
B78108E (axial leads, taped) Dimensions in mm



IND0429-B-E Minimum lead spacing 12.5 mm

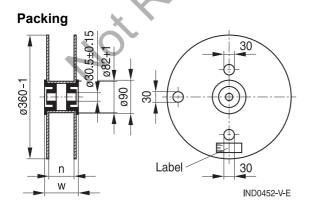
## B78148E (central radial leads, taped)

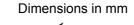
Dimensions in mm

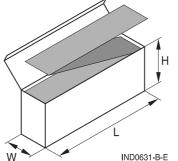




IND1244-N-E







n (mm): axial 72 + 1, w (mm): axial 84 max

axial 72 + 1, radial 42 + 1 axial 84 max., radial 54 max.

L x W x H (max. mm):

axial: 275 x 80 x 140, radial: 340 x 50 x 210



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## Technical data and measuring conditions

Rated inductance L <sub>R</sub>	Measured with LCR meter Agilent 4284A or impedance analyzer Agilent 4294A				
	Measuring current:	1 mA			
	Measuring temperature:	+20 °C			
Q factor Q <sub>min</sub>	Measured with impedance analyzer Agiler	nt 4294A, +20 °C			
Rated temperature T <sub>R</sub>	+40 °C				
Rated current I <sub>R</sub>	Maximum permissible DC current based on rated temper of +40 °C and component temperature of max. +125 °C				
Saturation current I <sub>sat</sub>	Max. permissible DC with inductance decrease				
	$\Delta L/L_0$ of approx. 10%, at +20 °C (Agilent	4284A and 42841A)			
DC resistance R <sub>max</sub>	Measured at +20 °C				
Resonance frequency f <sub>res,min</sub>	Measured with Agilent 4294A or 8753ES,	+20 °C			
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: (+245 ±5) °C, (3 ±0.3) s Wetting of soldering area: ≥ 90% (to IEC 60068-2-20, test Ta)				
Resistance to soldering heat	(+260 ±5)°C, 10 s (to IEC 60068-2-20, test Tb)				
Tensile strength of leads	≥ 20 N (to IEC 60068-2-21, test Ua)				
Climatic category	55/125/56 (to IEC 60068-1)				
Storage conditions	Mounted: -55 °C +125 °C Packaged: -25 °C +40 °C, ≤ 75% RH				
Weight	Approx. 0.38 g				



Mounting information:

When bending the leads, take care that the start-of-winding areas at the face ends (protected by glue and lacquer) are not subjected to any mechanical stress.



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## Characteristics and ordering codes

L <sub>R</sub>	Tolerance	$f_L$	Q <sub>min</sub>	f <sub>Q</sub>	I <sub>R</sub>	I <sub>sat</sub>	R <sub>max</sub>	f <sub>res, min</sub>	Ordering code 1)
μΗ		MHz		MHz	mA	mA	Ω	MHz	(reel packing) 2)
0.1	±20% ≘ M	1.0	50	7.96	7300	17000	0.015	700	B781*8E1101M000
0.15		1.0	50	7.96	6500	14500	0.017	650	B781*8E1151M000
0.22		1.0	55	7.96	5900	12200	0.019	610	B781*8E1221M000
0.33		1.0	60	7.96	5300	10100	0.023	480	B781*8E1331M000
0.47		1.0	60	7.96	5000	8500	0.027	400	B781*8E1471M000
0.68		1.0	60	7.96	4600	7100	0.031	360	B781*8E1681M000
1.0	±10% ≘ K	1.0	60	7.96	4150	5800	0.038	260	B781*8E1102K000
1.5		1.0	60	7.96	3800	4800	0.047	235	B781*8E1152K000
2.2		1.0	50	7.96	3400	4000	0.057	150	B781*8E1222K000
3.3		1.0	45	7.96	3050	3250	0.073	75	B781*8E1332K000
4.7		1.0	45	7.96	2750	2700	0.085	35	B781*8E1472K000
6.8		1.0	40	7.96	2450	2300	0.105	25	B781*8E1682K000
10		1.0	35	7.96	2250	2000	0.136	20	B781*8E1103K000
15		0.1	40	0.796	1600	1450	0.230	15	B781*8E1153K000
22		0.1	40	0.796	1300	1250	0.350	12	B781*8E1223K000
33	±5% ≘ J	0.1	50	0.796	1050	1000	0.550	9.0	B781*8E1333J000
47		0.1	40	0.796	950	870	0.680	8.0	B781*8E1473J000
68		0.1	45	0.796	780	720	0.900	6.5	B781*8E1683J000
100	2	0.1	60	0.796	640	580	1.450	6.0	B781*8E1104J000

<sup>1)</sup> Replace the \* by code number "0" for axial taping or by "4" for radial taping.

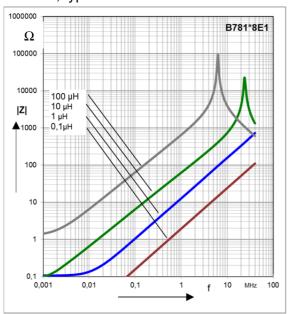
<sup>2)</sup> For Ammo pack the last digit has to be a "9". Example: B78108E1223K009

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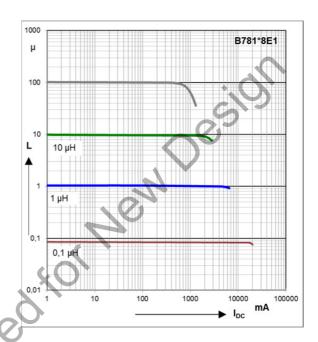
## Impedance |Z| versus frequency f

measured with impedance analyzer Agilent 4294A or S-parameter network analyzer Agilent 8753ES, typical values at +20 °C



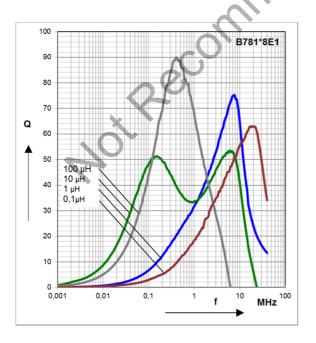
## Inductance L versus DC load current I<sub>DC</sub>

measured with LCR meter Agilent 4284A and 42841A, typical values at +20 °C



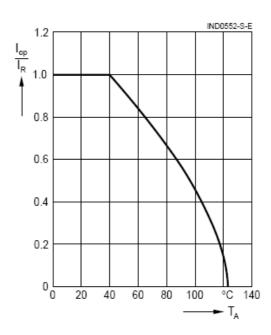
## Q factor versus frequency f

measured with impedance analyzer Agilent 4294A, typical values at +20 °C



# Current derating $I_{OP}/I_R$ versus ambient temperature $T_A$

(rated temperature  $T_R = +40 \,^{\circ}C$ )





#### **Cautions and warnings**

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
  - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
  - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pins only. Temperatures specified in relation to reflow soldering can also refer to the pins or terminals for products with larger thermal mass, as in such cases, the temperature difference to the top of the component is too big (e.g., high proportion of core within the component).
- If the components are to be washed or varnished it is necessary to check whether the washing or varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing or varnish agent residues to have a negative effect in the long-term on wire insulation.
  - Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
  - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure
    on the plastic housing or core. This pressure can have a deleterious effect on electrical properties,
    and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting, sealing, or varnishing materials used attack or destroy the wire, wire insulation, plastics or glue.
  - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
  - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obliged to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
  - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
  - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
  - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



### **Cautions and warnings**

## Display of ordering codes for TDK Electronics products

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#### Important notes

8 The trade names EPCOS, CarXield, CeraCharge, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CTVS, DeltaCap, DigiSiMic, FilterCap, FormFit, InsuGate, LeaXield, MediPlas, MiniBlue, MiniCell, MKD, MKK, ModCap, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PiezoBrush, PlasmaBrush, PowerHap, PQSine, PQvar, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SurfIND, ThermoFuse, WindCap, XieldCap are trademarks registered or pending in Europe and in other countries. Further information will be found on the Internet at www.tdk-electronics.tdk.com/trademarks.

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